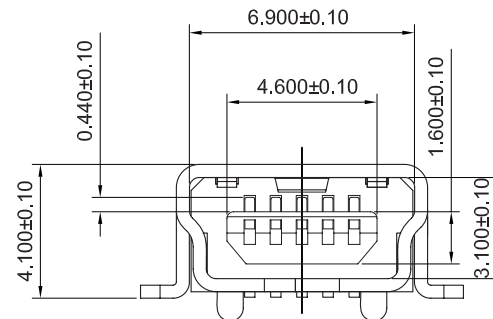
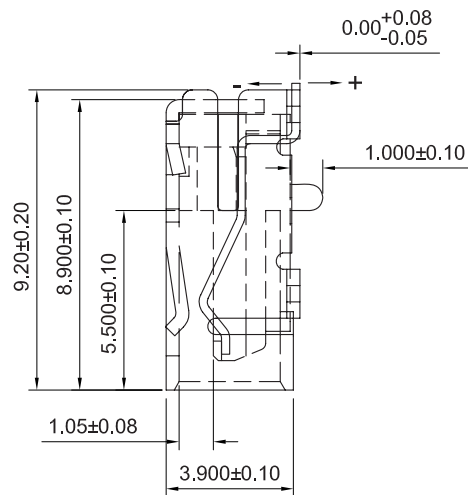
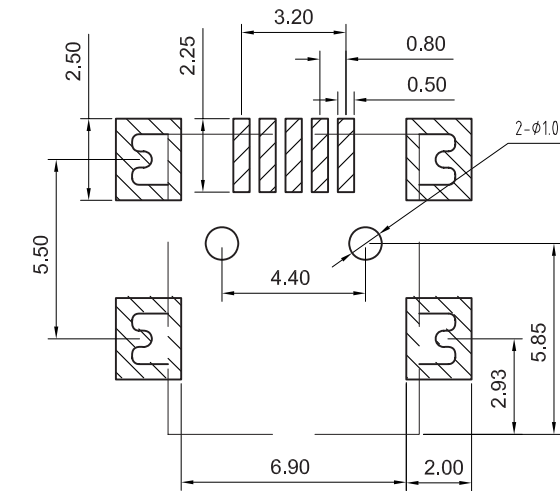


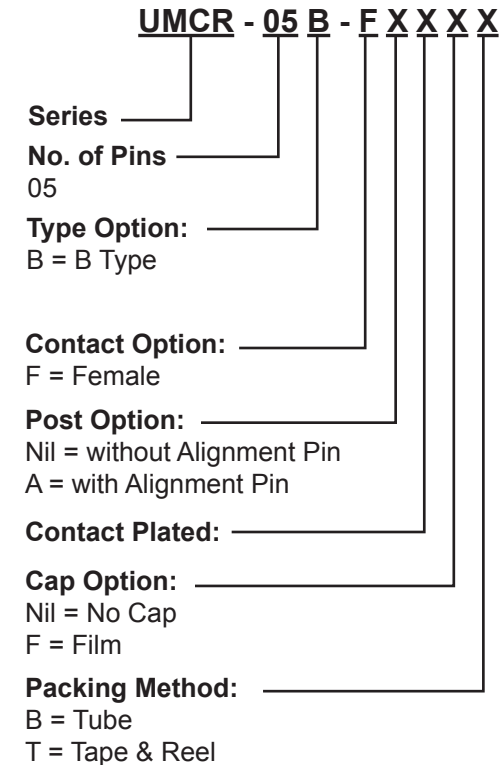
P.C. Board SMD Layout



Specifications

Current Rating: 1 Amp
 Dielectric Withstanding Voltage: 500 VAC for a minute.
 Contact Resistance: 30mΩ Max.
 Insulation Resistance: 1000MΩ min at DC 500V.
 Total Mating Force: 3.57kgf max.
 Total Unmating Force: 0.71kgf min.
 Temperature Rang: -55°C to 105°C
 Insulator: LCP UL94-V0 rated.
 Contact: Phosphor Bronze, t=0.25mm
 Contact Plating: Gold Flashed 1μ", 15μ", 30μ"
 Shell: Phosphor Bronze, t=0.4mm
 Shell Plating: Nickel plated.

Part Numbering System



* Contact Plating Option	Full Gold Plating	Gold Plated On Contact Area Tin Plated on Solder Area	Full Tin Plating
G : Gold Flash G10: Gold 10u" G15: Gold 15u" G30: Gold 30u"	S: Gold Flash S10: Gold 10u" S15: Gold 15u" S30: Gold 30u"	T: Tin 100u"	

General Tolerance	
X. ± 0.50	X.° ± 5°
.X ± 0.20	.X° ± 2°
.XX ± 0.10	.XX° ± 1°
Units : mm	